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# Electronic Filing System (EFS) Data

## Electronic Patent Application Submission

### USPTO Use Only

EFS ID: 53326

Application ID: 10667759



Title of Invention: METHODS OF MAKING THIN  
INTEGRATED CIRCUIT DEVICE  
PACKAGES WITH IMPROVED  
THERMAL PERFORMANCE

First Named Inventor: Sean Crowley

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-22

Effective Receipt Date: 2004-01-08

Submission Type: Information Disclosure  
Statement

Filing Type:

Confirmation number: 1384

Attorney Docket Number: AMKOR022CB

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US

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## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	METHODS OF MAKING THIN INTEGRATED CIRCUIT DEVICE PACKAGES WITH IMPROVED THERMAL PERFORMANCE	
Application Number:	10/667759 	
Date:	2003-09-22	
First Named Applicant:	Sean T. Crowley	
Confirmation Number:	1384	
Attorney Docket Number:	AMKOR022CB	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids1-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention	METHODS OF MAKING THIN INTEGRATED CIRCUIT DEVICE PACKAGES WITH IMPROVED THERMAL PERFORMANCE						
Application Number:	10/667759 						
Confirmation Number:	1384						
First Named Applicant:	Sean Crowley						
Attorney Docket Number:	AMKOR022CB						
Art Unit:	2811						
Search string:	( 2596993 or 3435815 or 3734660 or 3838984 or 4054238 or 4189342 or 4258381 or 4289922 or 4301464 or 4332537 or 4417266 or 4451224 or 4530152 or 4541003 or 4646710 or 4707724 or 4727633 or 4737839 or 4756080 or 4812896 or 4862245 or 4862246 or 4907067 or 4920074 or 4935803 or 4942454 or 4987475 or 5018003 or 5029386 or 5041902 or 5057900 or 5059379 or 5065223 or 5070039 or 5087961 or 5091341 or 5096852 or 5118298 or 5151039 or 5157475 or 5157480 or 5168368 or 5172213 or 5172214 or 5175060 or 5200362 or 5200809 or 5214845 or 5216278 or 5218231 or 20010008305 or 20010014538 or 20010011654 or 20020024122 or 20020027297 or 20020140061 or 20020140068 or 20020163015 or 20030030131 or 20030073265 ).pn.						
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	3435815	1969-04-01	FORCIER			
	3	3734660	1973-05-22	DAVIES ET AL.			
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## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
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	10	20030073265	2003-04-17	HU ET AL.			

Signature

Examiner Name	Date